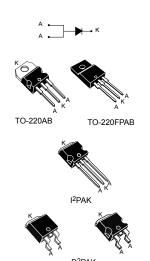




## 100 V, 20 A power Schottky rectifier



#### **Features**

- · Low forward voltage drop meaning very small conduction losses
- · Avalanche rated
- · Low frequency operation
- Insulated package TO-220FPAB:
  - Insulating voltage = 2000 V<sub>RMS</sub> sine
- ECOPACK<sup>®</sup>2 compliant component for D<sup>2</sup>PAK on demand

### **Applications**

- · Switching diode
- SMPS
- DC/DC converter
- LED lighting
- · Adapter for notebook and game station

### **Description**

This single Schottky rectifier is suited for high frequency switch mode power supply.

Packaged in TO-220AB, TO-220FPAB, D²PAK and I²PAK, the STPS20M100S is intended to be used in notebook, game station and desktop adaptors, providing in these applications a good efficiency at both low and high load.

Product status link
STPS20M100S

Product summary				
I <sub>F(AV)</sub>	20 A			
V <sub>RRM</sub>	100 V			
V <sub>F</sub> (typ.)	0.61 V			
T <sub>j</sub> (max.)	150 °C			



## 1 Characteristics

Table 1. Absolute ratings (limiting values with anode terminals short circuited, at 25 °C unless otherwise specified)

Symbol	Parame	Value	Unit		
V <sub>RRM</sub>	Repetitive peak reverse voltage			100	V
I <sub>F(RMS)</sub>	Forward rms current			30	Α
I <sub>F(AV)</sub>	Average forward current $\delta$ = 0.5, square wave		$T_{C} = 130  ^{\circ}\text{C}$		Α
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$			350	Α
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p = 10 \mu s$ , $T_j = 125 °C$			1150	W
T <sub>stg</sub>	Storage temperature range				°C
Tj	Maximum operating junction temperature (1)			+150	°C

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameter

Symbol		Value	Unit		
Ru a	R <sub>th(j-c)</sub> Junction to case	TO-220AB, D <sup>2</sup> PAK, I <sup>2</sup> PAK	1.2	°C/W	
'`tn(j-c)		TO-220FPAB	4	C/VV	

For more information, please refer to the following application note:

AN5088: Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test co	Min.	Тур.	Max.	Unit	
		T <sub>j</sub> = 25 °C	V <sub>R</sub> = 70 V	-	5		μA
I <sub>R</sub> <sup>(1)</sup>	Povorco logicado current	T <sub>j</sub> = 125 °C		-	5		mA
'R'	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = 100 V	-	10	40	μA
		T <sub>j</sub> = 125 °C	v <sub>R</sub> = 100 v	-	10	40	mA
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A	-	550		
		T <sub>j</sub> = 125 °C		-	455		
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C		-	660	730	mV
VF \	Polward voltage drop	T <sub>j</sub> = 125 °C		-	530	600	IIIV
	$T_{j} = 25 ^{\circ}\text{C}$ $T_{j} = 125 ^{\circ}\text{C}$	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 20 A	-	775	850	
		1F - 20 M	-	610	690		

<sup>1.</sup> Pulse test:  $t_p = 5$  ms,  $\delta < 2\%$ 

DS6169 - Rev 5 page 2/15

<sup>2.</sup> Pulse test:  $t_p = 380 \ \mu s, \ \delta < 2\%$ 



To evaluate the conduction losses, use the following equation:

$$P = 0.425 \times I_{F(AV)} + 0.0088 \times I_{F}^{2} (RMS)$$

For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

### 1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (anode terminals short circuited)

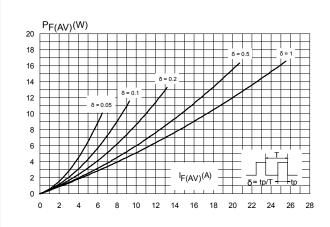


Figure 2. Average forward current versus ambient temperature ( $\delta$  = 0.5, anode terminals short circuited)

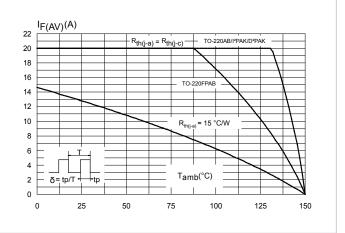


Figure 3. Normalized avalanche power derating versus pulse duration ( $T_i = 125\,^{\circ}C$ )

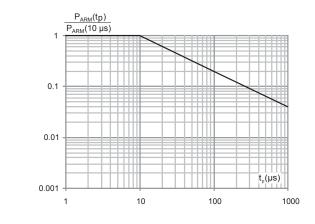
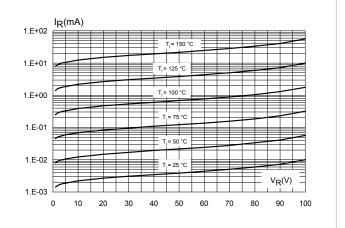


Figure 4. Reverse leakage current versus reverse voltage applied (typical values)



DS6169 - Rev 5 page 3/15



Figure 5. Relative variation of thermal impedance junction to case versus pulse duration (TO-220AB, D²PAK, I²PAK)

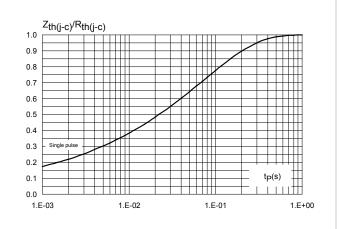


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB)

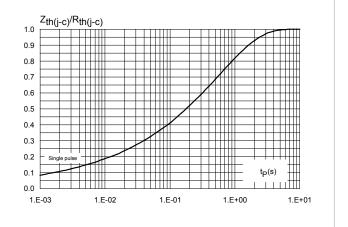


Figure 7. Junction capacitance versus reverse voltage applied (typical values)

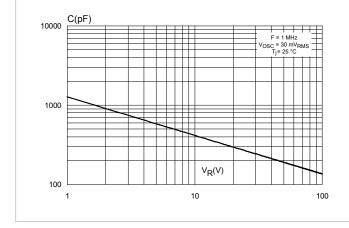


Figure 8. Forward voltage drop versus forward current (anode terminals short circuited)

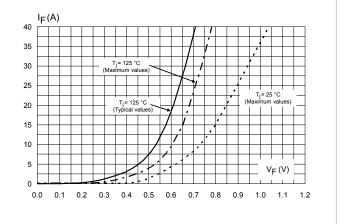
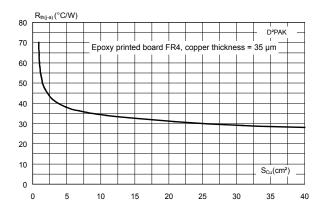


Figure 9. Thermal resistance junction to ambient versus copper surface under tab for D2PAK



DS6169 - Rev 5 page 4/15



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

### 2.1 TO-220AB package information

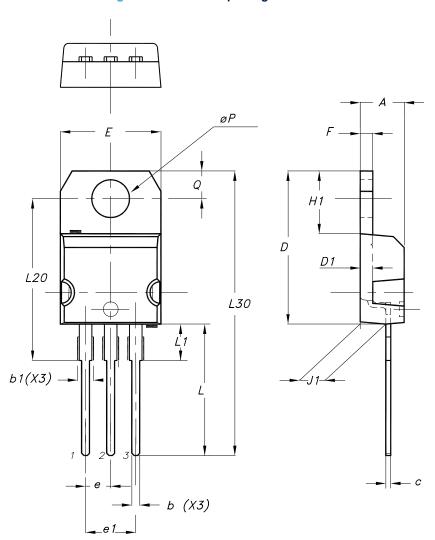
• Epoxy meets UL 94,V0

• Cooling method: by conduction (C)

Recommended torque value: 0.55 N·m

Maximum torque value: 0.70 N·m

Figure 10. TO-220AB package outline



DS6169 - Rev 5 page 5/15



Table 4. TO-220AB package mechanical data

	Dimensions				
Ref.	Millimeters		Inches (for re	ference only)	
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
b	0.61	0.88	0.240	0.035	
b1	1.14	1.55	0.045	0.061	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27	' typ.	0.050	typ.	
E	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40 typ.		0.646	typ.	
L30	28.90 typ.		1.138	typ.	
θР	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	

DS6169 - Rev 5 page 6/15



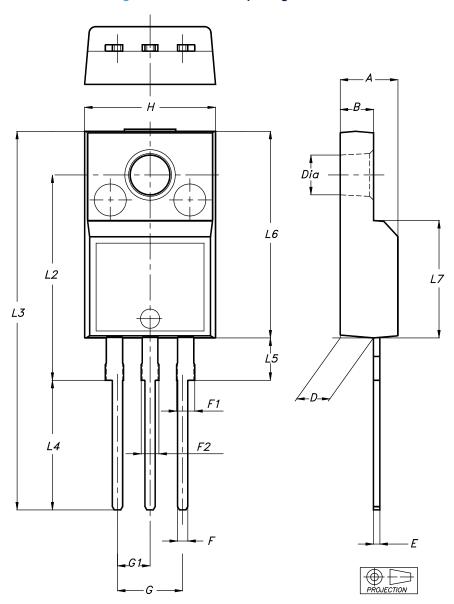
## 2.2 TO-220FPAB package information

Epoxy meets UL 94,V0

Cooling method: by conduction (C)
 Recommended torque value: 0.55 N·m

• Maximum torque value: 0.70 N·m

Figure 11. TO-220FPAB package outline



DS6169 - Rev 5 page 7/15



Table 5. TO-220FPAB package mechanical data

	Dimensions				
Ref.	Millin	neters	Inches (for reference only)		
	Min. Max.		Min.	Max.	
Α	4.40	4.60	0.1739	0.1818	
В	2.50	2.70	0.0988	0.1067	
D	2.50	2.75	0.0988	0.1087	
E	0.45	0.70	0.0178	0.0277	
F	0.75	1.00	0.0296	0.0395	
F1	1.15	1.70	0.0455	0.0672	
F2	1.15	1.70	0.0455	0.0672	
G	4.95	5.20	0.1957	0.2055	
G1	2.40	2.70	0.0949	0.1067	
Н	10.00	10.40	0.3953	0.4111	
L2	16.00	0 typ.	0.632	4 typ.	
L3	28.60	30.60	1.1304	1.2095	
L4	9.80	10.60	0.3874	0.4190	
L5	2.90	3.60	0.1146	0.1423	
L6	15.90	16.40	0.6285	0.6482	
L7	9.00	9.30	0.3557	0.3676	
Dia	3.00	3.20	0.1186	0.1265	

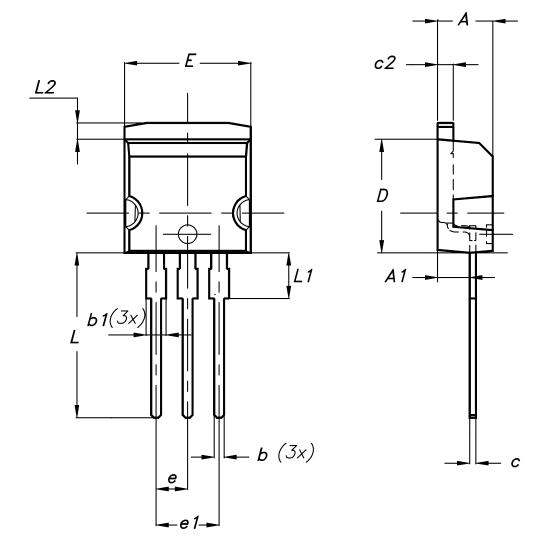
DS6169 - Rev 5 page 8/15



## 2.3 I<sup>2</sup>PAK package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)

Figure 12. I<sup>2</sup>PAK package outline



DS6169 - Rev 5 page 9/15



Table 6. I<sup>2</sup>PAK package mechanical data

	Dimensions				
Ref.	Millin	Millimeters		eference only)	
	Min.	Max.	Min.	Max.	
A	4.40	4.60	0.173	0.181	
A1	2.40	2.72	0.094	0.107	
b	0.61	0.88	0.024	0.035	
b1	1.14	1.70	0.044	0.067	
С	0.49	0.70	0.019	0.028	
c2	1.23	1.32	0.048	0.052	
D	8.95	9.35	0.352	0.368	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
Е	10.00	10.40	0.394	0.409	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L2	1.27	1.40	0.050	0.055	

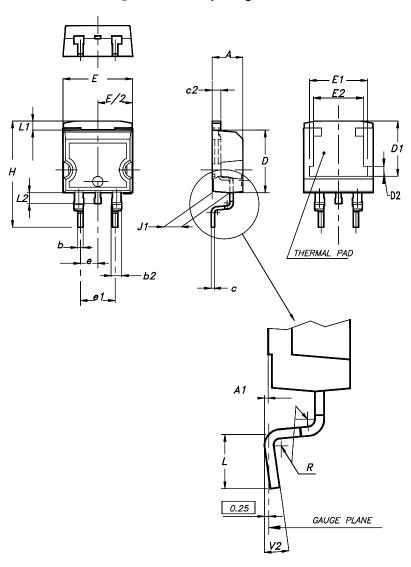
DS6169 - Rev 5 page 10/15



## 2.4 D<sup>2</sup>PAK package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

Figure 13. D<sup>2</sup>PAK package outline



Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

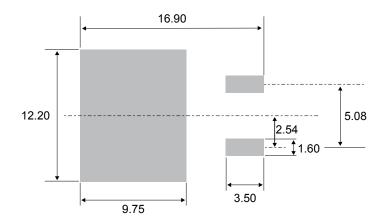
DS6169 - Rev 5 page 11/15



Table 7. D<sup>2</sup>PAK package mechanical data

	Dimensions				
Ref.	Millin	neters	Inches (for re	eference only)	
	Min.	Max.	Min.	Max.	
A	4.36	4.60	0.172	0.181	
A1	0.00	0.25	0.000	0.010	
b	0.70	0.93	0.028	0.037	
b2	1.14	1.70	0.045	0.067	
С	0.38	0.69	0.015	0.027	
c2	1.19	1.36	0.047	0.053	
D	8.60	9.35	0.339	0.368	
D1	6.90	8.00	0.272	0.311	
D2	1.10	1.50	0.043	0.060	
E	10.00	10.55	0.394	0.415	
E1	8.10	8.90	0.319	0.346	
E2	6.85	7.25	0.266	0.282	
е	2.54	typ.	0.1	100	
e1	4.88	5.28	0.190	0.205	
Н	15.00	15.85	0.591	0.624	
J1	2.49	2.90	0.097	0.112	
L	1.90	2.79	0.075	0.110	
L1	1.27	1.65	0.049	0.065	
L2	1.30	1.78	0.050	0.070	
R	0.4	typ.	0.0	)15	
V2	0°	8°	0°	8°	

Figure 14. D<sup>2</sup>PAK recommended footprint (dimensions in mm)



DS6169 - Rev 5 page 12/15



# **3** Ordering information

**Table 8. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS20M100ST	PS20M100ST	TO-220AB	1.95 g	50	Tube
STPS20M100SFP	PS20M100SFP	TO-220FPAB	1.90 g	50	Tube
STPS20M100SR	PS20M100SR	I²PAK	1.50 g	50	Tube
STPS20M100SG-TR	PS20M100SG	D²PAK	1.48 g	1000	Tape and reel

DS6169 - Rev 5 page 13/15



# **Revision history**

Table 9. Document revision history

Date	Version	Changes
25-Mar-2009	1	First issue.
16-Apr-2010	2	Updated package graphic for TO-220AB on front page and in Table 5.
24-May-2016	3	Updated cover page.  Complete Characteristics section update.  Updated Section 2.4: "D²PAK package information" and Table 9: "Ordering information".
28-Sep-2018	4	Updated cover page, Table 1. Absolute ratings (limiting values with anode terminals short circuited, at 25 °C unless otherwise specified) and Table 8. Ordering information.  Removed figure 1 and figure 11.  Minor text changes to improve readability.
18-Feb-2019	5	Updated Table 1.

DS6169 - Rev 5 page 14/15



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DS6169 - Rev 5 page 15/15